

N-Channel Enhancement Mode MOSFET

TDM3744

**DESCRIPTION**

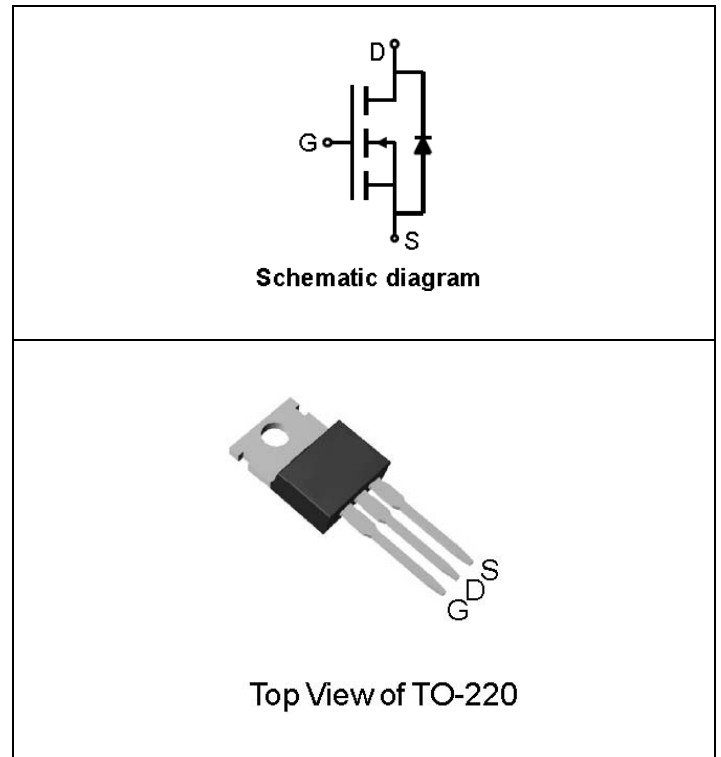
The TDM3744 uses advanced trench technology to provide excellent RDS(ON) and low gate charge. This device is suitable for use as a load switch or in PWM applications.

**GENERAL FEATURES**

- 80V/196A  
RDS(ON) < 3.9mΩ @ VGS=10V
- High Power and current handling capability
- Lead free product is available
- TO220 Package

**Application**

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- Power Tools
- UPS
- Motor Control



ABSOLUTE MAXIMUM RATINGS(T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	80	V
Gate-Source Voltage	V <sub>GS</sub>	+20	V
Drain Current @ Continuous(Silicon Limited)	I <sub>D</sub> (T <sub>C</sub> =25°C)	196	A
	I <sub>D</sub> (T <sub>C</sub> =100°C)	139	A
Drain Current @ Continuous(Package Limited)	I <sub>D</sub> (T <sub>C</sub> =25°C)	180	A
Drain Current @ Current-Pulsed	I <sub>DM</sub> (T <sub>C</sub> =25°C)	500	A
Maximum Power Dissipation	P <sub>D</sub> (T <sub>C</sub> =25°C)	272	W
Avalanche Energy, Single Pulse	E <sub>AS</sub> (L=0.5mH,T <sub>C</sub> =25°C)	306	mJ
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 175	°C

THERMAL CHARACTERISTICS

Thermal Resistance,Junction-to-Ambient (Note 2)	R <sub>θJA</sub>	60	°C/W
Thermal Resistance,Junction-to-Case	R <sub>θJC</sub>	0.55	°C/W

**ELECTRICAL CHARACTERISTICS** ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>STATIC CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	80	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V, T_j=25^{\circ}\text{C}$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3	4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	3.2	3.9	$m\Omega$
Transconductance	$g_{fs}$	$V_{DS}=5V, I_D=20A$	-	70	-	S
Gate Resistance	$R_G$	$V_{DS}=0V, V_{GS}=0V, F=1.0\text{MHz}$	-	1.3	-	$\Omega$
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=40V, V_{GS}=0V, F=1.0\text{MHz}$	-	3635	-	PF
Output Capacitance	$C_{oss}$		-	1317	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	91	-	PF
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=40V, V_{GS}=10V, R_G=10\Omega, I_D=20A$	-	13	-	nS
Turn-on Rise Time	$t_r$		-	18	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	44	-	nS
Turn-Off Fall Time	$t_f$		-	25	-	nS
Total Gate Charge	$Q_g$	$V_{DD}=40V, I_D=20A, V_{GS}=10V$	-	74	-	nC
Gate-Source Charge	$Q_{gs}$		-	17	-	nC
Gate-Drain Charge	$Q_{gd}$		-	31	-	nC
<b>REVERSE DIODE CHARACTERISTICS</b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=20A$	-	0.9	1.2	V
Body Diode Reverse Recovery Time	$T_{rr}$	$I_F=20A, di/dt=400A/\mu s$	-	44	-	nS
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	155	-	nC

Typical Operating Characteristics

Fig 1. Typical Output Characteristics

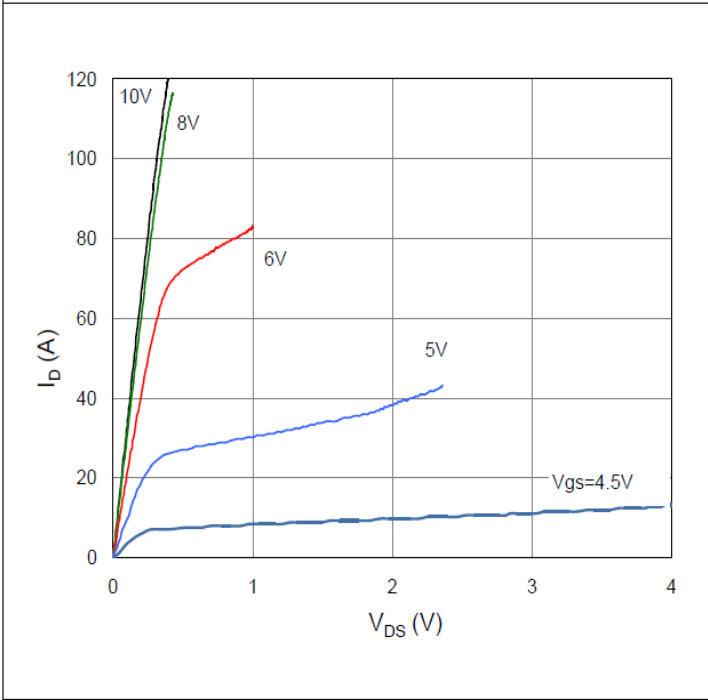


Figure 2. On-Resistance vs. Gate-Source Voltage

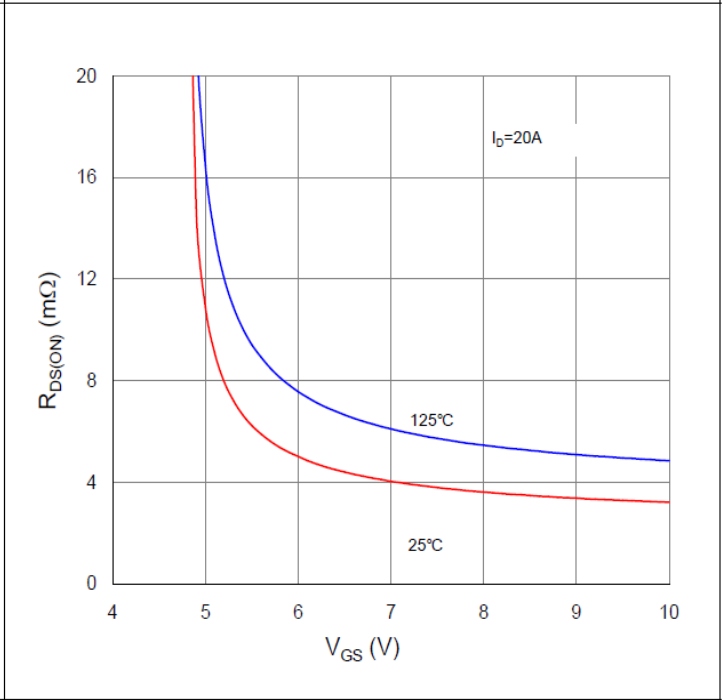


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

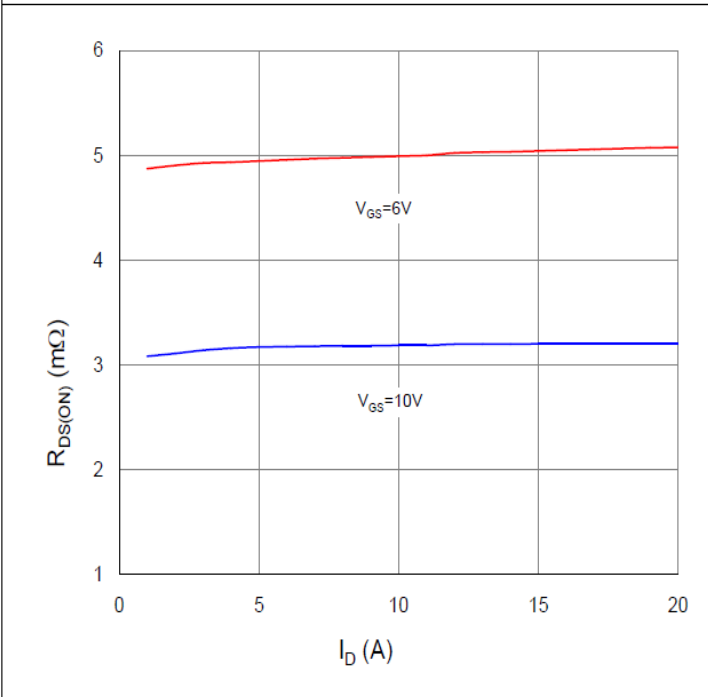
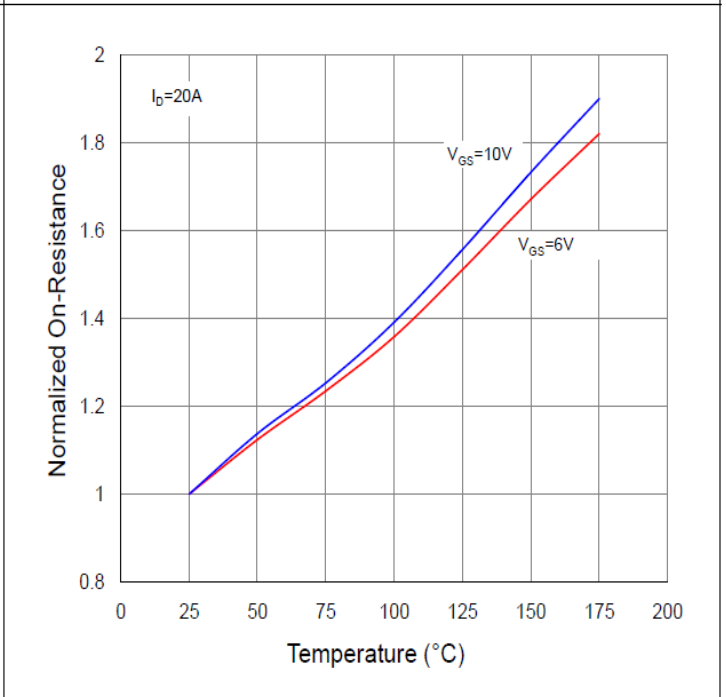


Figure 4. Normalized On-Resistance vs. Junction Temperature



Typical Operating Characteristics(Cont.)

Figure 5. Typical Transfer Characteristics

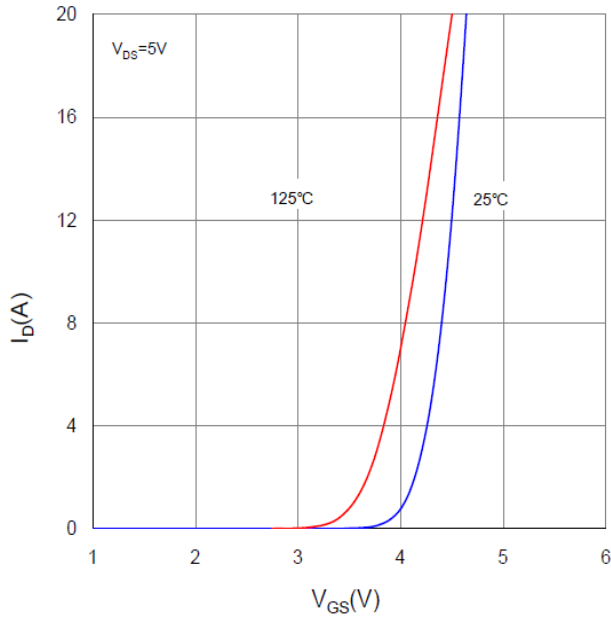


Figure 6. Typical Source-Drain Diode Forward Voltage

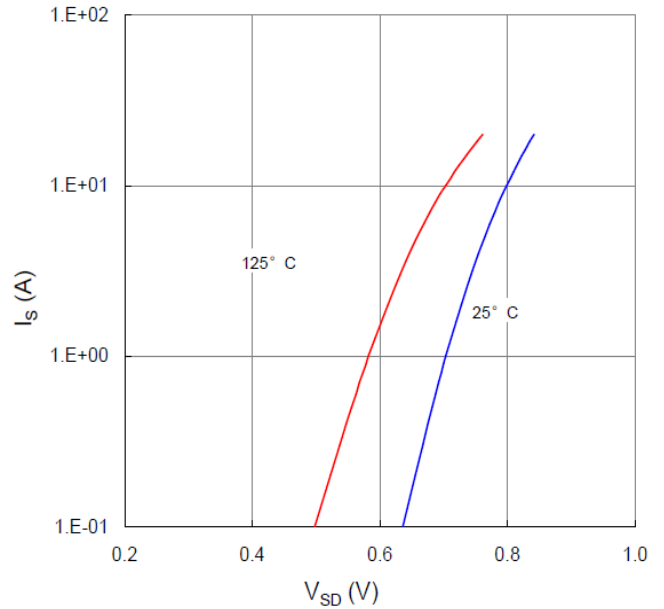


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

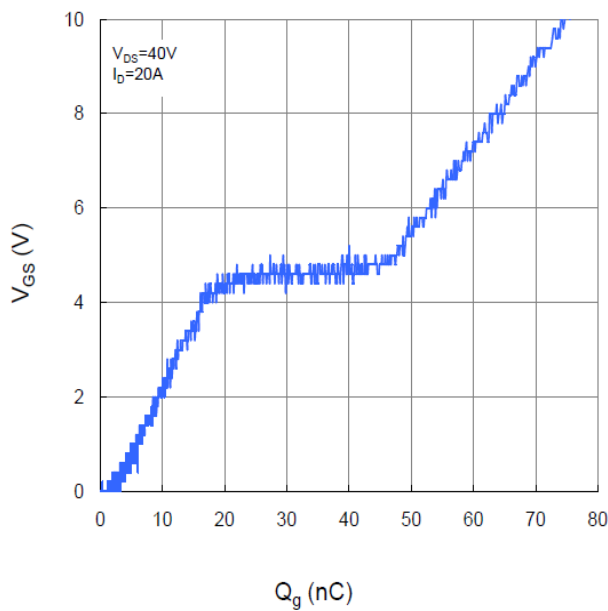
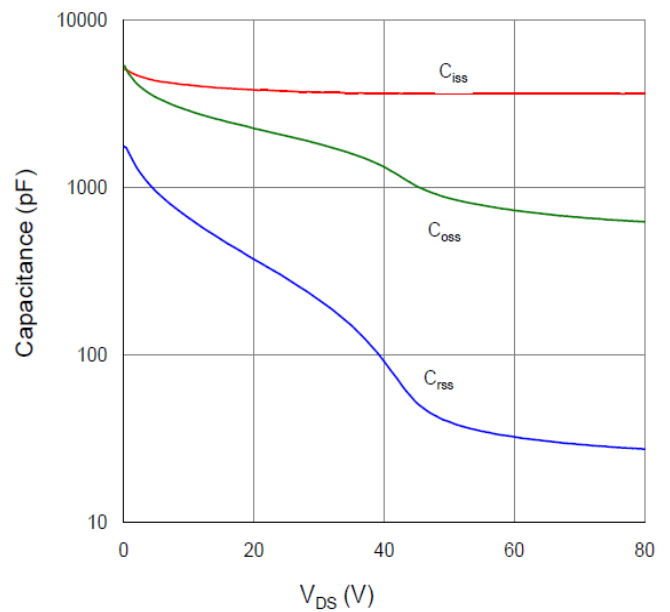


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage



Typical Operating Characteristics (Cont.)

Figure 9. Maximum Safe Operating Area

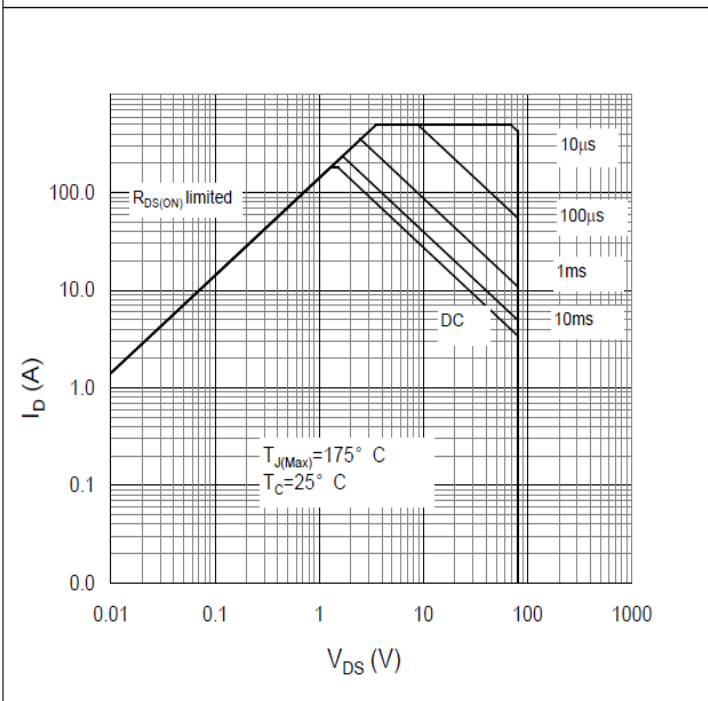


Figure 10. Maximum Drain Current vs. Case Temperature

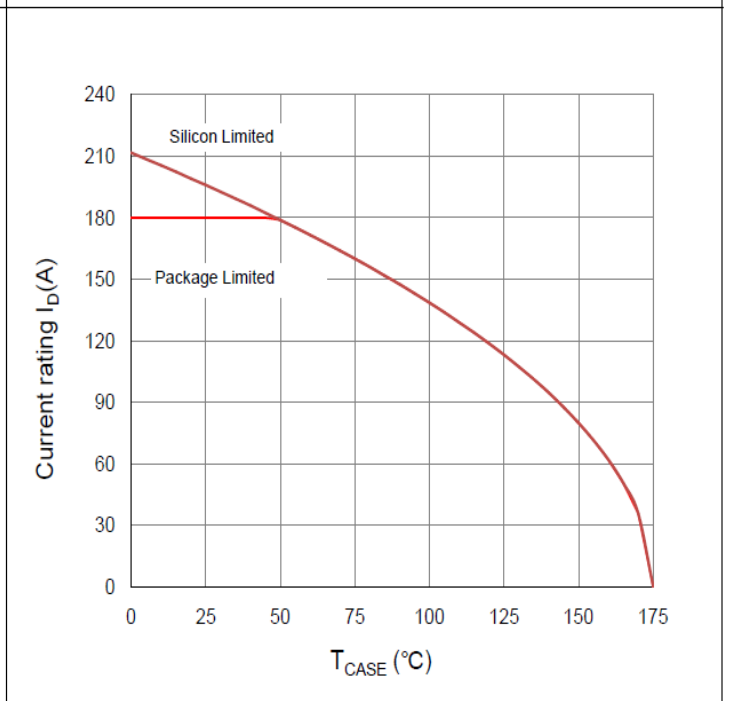
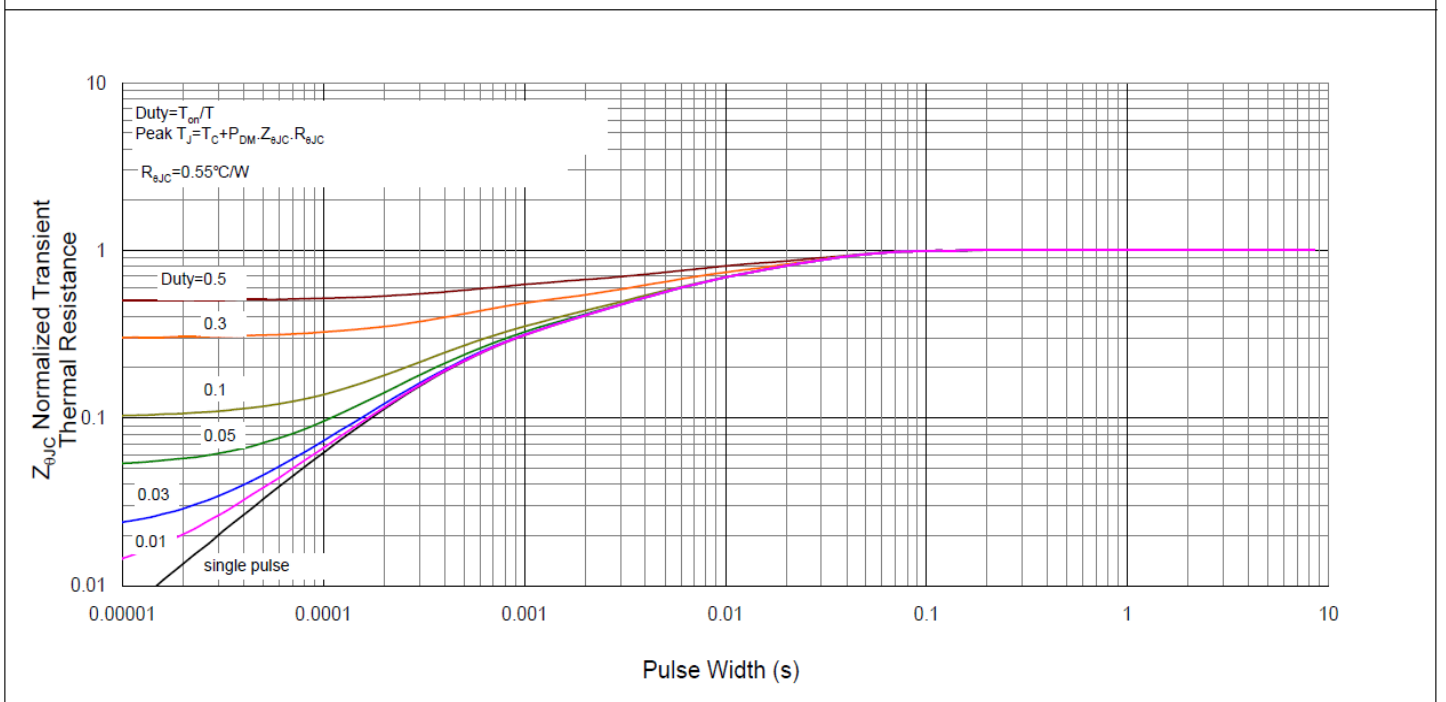
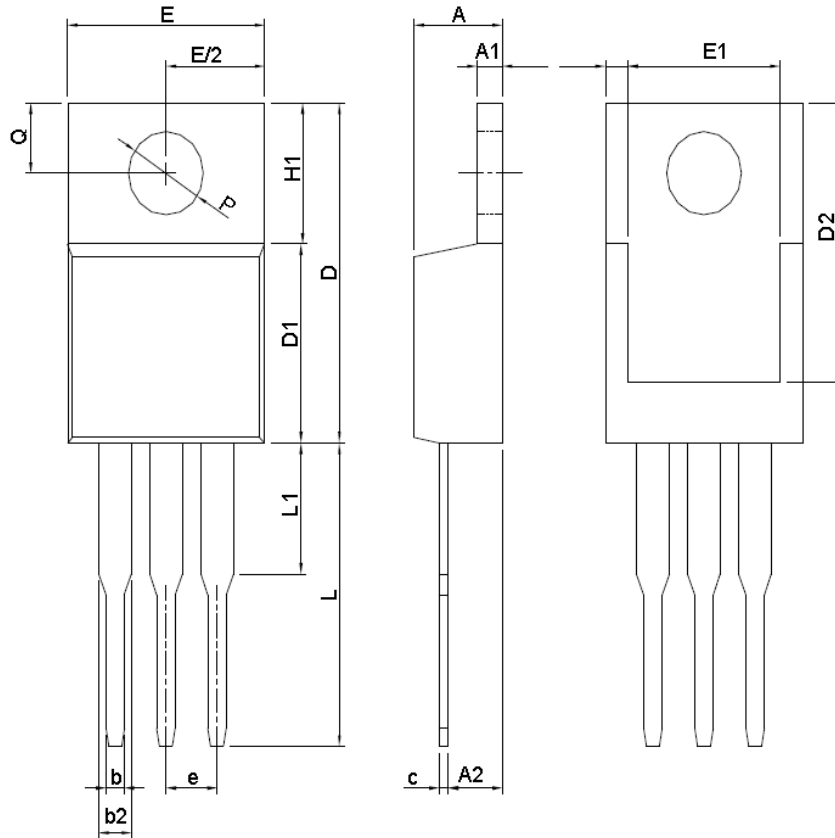


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case



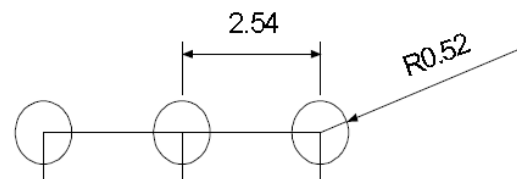
Package Information

TO220 Package



SYMBOL	TO-220			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	3.56	4.83	0.140	0.190
A1	0.51	1.40	0.020	0.055
A2	2.03	2.92	0.080	0.115
b	0.38	1.02	0.015	0.040
b2	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.22	16.51	0.560	0.650
D1	8.38	9.30	0.330	0.366
D2	12.19	13.65	0.480	0.537
E	9.65	10.67	0.380	0.420
E1	6.86	8.89	0.270	0.350
e	2.54 BSC		0.100 BSC	
H1	5.84	6.86	0.230	0.270
L	12.70	14.73	0.500	0.580
L1	-	6.35	-	0.250
P	3.53	4.09	0.139	0.161
Q	2.54	3.43	0.100	0.135

RECOMMENDED LAND PATTERN



UNIT: mm

Design Notes

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